Product / Package Information

Package	LGA_CAV
Body Size (mm)	3 X 4 X 1.0
Ball Count	5
Terminal Finish	Gold

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant

Materials Declaration

Lid/Shield

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Stainless steel	Iron	7439-89-6	7.20 E-03	71.95	719539	27.97	279702
Stainless steel	Chromium	7440-47-3	1.81 E-03	18.09	180884	7.03	70314
Stainless steel	Nickel	7440-02-0	8.10 E-04	8.09	80948	3.15	31466
Stainless steel	Manganese	7439-96-5	1.27 E-04	1.27	12692	0.49	4934
Stainless steel	Silicon	7440-21-3	5.20 E-05	0.52	5197	0.20	2020
Stainless steel	Carbon	7440-44-0	4.90 E-06	0.05	490	0.02	190
Stainless steel	Phosphorus	7723-14-0	2.30 E-06	0.02	230	0.01	89
Stainless steel	Sulfur	7704-34-9	2.00 E-07	0.002	20	0.00	8
Subtotal			1.00 E-02	100.0	1000000	38.87	388723

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Laminate	Proprietary	8.66 E-03	70.65	706458	33.66	336574
Copper & its alloys	Copper	7440-50-8	2.14 E-03	17.46	174576	8.32	83172
Other organic materials	Solder Mask	Proprietary	7.18 E-04	5.85	58545	2.79	27892
Nickel & its alloys	Nickel	7440-02-0	5.99 E-04	4.88	48842	2.33	23270
Precious Metals	Gold	7440-57-5	1.42 E-04	1.16	11579	0.55	5516
Subtotal			1.23 E-02	100.00	1000000	47.64	476425

Solder Land

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.80 E-04	73.68	736842	1.09	10877
Nickel & its alloys	Nickel	7440-02-0	8.00 E-05	21.05	210526	0.31	3108
Precious Metals	Gold	7440-57-5	2.00 E-05	5.26	52632	0.08	777
Subtotal			3.80 E-04	100.00	1000000	1.48	14762

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.86 E-05	99	990000	0.27	2665
Precious metals	Palladium	7440-05-3	6.93 E-07	1	10000	0.00	27
Subtotal			6.93 E-05	100	1000000	0.27	2692

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.70 E-03	100	1000000	6.60	66041

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.39 E-04	73.40	734000	2.48	24836
Thermoset	Resin	Proprietary	1.60 E-04	18.35	183500	0.62	6209
Other inorganic materials	Metal Oxide	Proprietary	2.40 E-05	2.75	27500	0.09	930
Others	Amine	Proprietary	2.40 E-05	2.75	27500	0.09	930
Other organic materials	Gamma Butyrolactone	96-48-0	2.40 E-05	2.75	27500	0.09	930
Subtotal			8.71 E-04	100.00	1000000	3.38	33836

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.24 E-04	55	550000	0.48	4829
Other organic materials	Bis/Naphtalene Epoxy Resin	27610-48-6	4.52 E-05	20	200000	0.18	1756
Other organic materials	Organic Acid Anhydride	Proprietary	3.39 E-05	15	150000	0.13	1317
Others	Additives	Proprietary	1.02 E-05	4.5	45000	0.04	395
Other organic materials	Bis A Epoxy Resin	25068-38-6	5.65 E-06	2.5	25000	0.02	219
Other organic materials	Phenolic Resin	Proprietary	5.65 E-06	2.5	25000	0.02	219
Other inorganic materials	Carbon Black	1333-86-4	1.13 E-06	0.5	5000	0.004	44
Subtotal			2.26 E-04	100.00	1000000	0.88	8780

Lid/ Shield Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.69 E-04	75.0	193743	0.66	6556
Other organic materials	Bisphenof F type epoxy resin	9003-36-5	2.25 E-05	10.0	25832	0.09	874
Other organic materials	Bisphenof A type epoxy resin	25068-38-6	2.25 E-05	10.0	25832	0.09	874
Others	Additives	Proprietary	6.75 E-06	3.0	7750	0.03	262
Others	Curing Agent	Proprietary	4.50 E-06	2.0	5166	0.02	175
Subtotal			2.25 E-04	100.00	258324	0.87	8741

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.57 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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